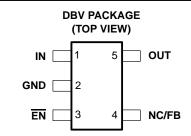
SLVS203E - JUNE 1999 - REVISED MAY 2001

- 100-mA Low-Dropout Regulator
- Available in 1.2-V, 1.5-V, 1.8-V, 2.5-V, 2.7-V, 2.8-V, 3.0-V, 3.3-V, and 5-V Fixed-Output and Adjustable Versions
- Only 17 μA Quiescent Current at 100 mA
- 1 μA Quiescent Current in Standby Mode
- Dropout Voltage Typically 71 mV at 100mA
- Over Current Limitation
- –40°C to 125°C Operating Junction Temperature Range
- 5-Pin SOT-23 (DBV) Package

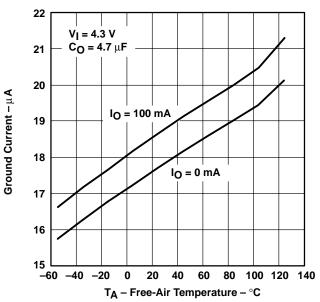
description

The TPS769xx family of low-dropout (LDO) voltage regulators offers the benefits of low dropout voltage, ultralow-power operation, and miniaturized packaging. These regulators feature low dropout voltages and ultralow quiescent current compared to conventional LDO regulators. Offered in a 5-terminal small outline integrated-circuit SOT-23 package, the TPS769xx series devices are ideal for micropower operations and where board space is at a premium.

A combination of new circuit design and process innovation has enabled the usual PNP pass transistor to be replaced by a PMOS pass element. Because the PMOS pass element behaves as a low-value resistor, the dropout voltage is very low, typically 71 mV at 100 mA of







load current (TPS76950), and is directly proportional to the load current. Since the PMOS pass element is a voltage-driven device, the quiescent current is ultralow (28 µA maximum) and is stable over the entire range of output load current (0 mA to 100 mA). Intended for use in portable systems such as laptops and cellular phones, the ultralow-dropout voltage feature and ultralow-power operation result in a significant increase in system battery operating life.

The TPS769xx also features a logic-enabled sleep mode to shut down the regulator, reducing quiescent current to 1 μ A typical at T_J = 25°C. The TPS769xx is offered in 1.2-V, 1.5-V, 1.8-V, 2.5-V, 2.7-V, 2.8-V, 3.0-V, 3.3-V, and 5-V fixed-voltage versions and in a variable version (programmable over the range of 1.2 V to 5.5 V).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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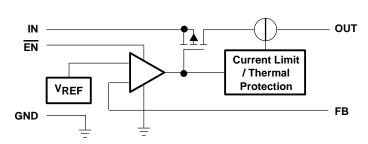
AVAILABLE OPTIONS

TJ	VOLTAGE	PACKAGE	PART N	UMBER	SYMBOL
	Variable 1.2V to 5.5V		TPS76901DBVT†	TPS76901DBVR‡	PCFI
	1.2 V		TPS76912DBVT [†]	TPS76912DBVR‡	PCGI
	1.5 V		TPS76915DBVT [†]	TPS76915DBVR‡	PCHI
	1.8 V		TPS76918DBVT†	TPS76918DBVR‡	PCII
–40°C to 125°C	2.5 V	SOT-23 (DBV)	TPS76925DBVT [†]	TPS76925DBVR‡	PCJI
	2.7 V	(000)	TPS76927DBVT [†]	TPS76927DBVR‡	PCKI
	2.8 V		TPS76928DBVT [†]	TPS76928DBVR [‡]	PCLI
	3.0 V		TPS76930DBVT†	TPS76930DBVR‡	PCMI
	3.3 V		TPS76933DBVT†	TPS76933DBVR‡	PCNI
	5.0 V		TPS76950DBVT†	TPS76950DBVR‡	PCOI

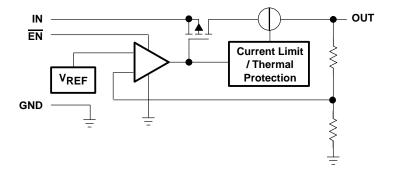
[†]The DBVT indicates tape and reel of 250 parts.

functional block diagram

TPS76901



TPS76912/15/18/25/27/28/30/33/50



[‡] The DBVR indicates tape and reel of 3000 parts.

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Terminal Functions

TERMIN	AL		DESCRIPTION					
NAME	NO.	1/0	DESCRIPTION					
GND	2		Ground					
EN	3	- 1	Enable input					
FB	4	1	edback voltage (TPS76901 only)					
IN	1	ı	Input supply voltage					
NC	4		No connection (Fixed options only)					
OUT	5	0	Regulated output voltage					

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Input voltage range (see Note 1)	0.3 V to 13.5 V
Voltage range at EN	
Voltage on OUT, FB	7 V
Peak output current	Internally limited
ESD rating, HBM	2 kV
Continuous total power dissipation	See Dissipation Rating Table
Operating virtual junction temperature range, T _J	–40°C to 150°C
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network ground terminal.

DISSIPATION RATING TABLE

BOARD	PACKAGE	$R_{ heta}$ JC	$R_{\theta JA}$	DERATING FACTOR ABOVE T _A = 25°C	$T_A \le 25^{\circ}C$ POWER RATING	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
Low K‡	DBV	65.8 °C/W	259 °C/W	3.9 mW/°C	386 mW	212 mW	154 mW
High K§	DBV	65.8 °C/W	180 °C/W	5.6 mW/°C	555 mW	305 mW	222 mW

[‡] The JEDEC Low K (1s) board design used to derive this data was a 3 inch x 3 inch, two layer board with 2 ounce copper traces on top of the board. § The JEDEC High K (2s2p) board design used to derive this data was a 3 inch x 3 inch, multilayer board with 1 ounce internal power and ground planes and 2 ounce copper traces on top and bottom of the board.

recommended operating conditions

	MIN	NOM MAX	UNIT
Input voltage, V _I (see Note 2)	2.7	10	V
Output voltage range, VO	1.2	5.5	V
Continuous output current, IO (see Note 3)	0	100	mA
Operating junction temperature, T _J	-40	125	°C

NOTES: 2. To calculate the minimum input voltage for your maximum output current, use the following formula: $V_I(min) = V_O(max) + V_{DO}$ (max load)

3. Continuous output current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.



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electrical characteristics over recommended operating free-air temperature range, V_I = V_{O(typ)} + 1 V, I_O = 100 mA, $\overline{\text{EN}}$ = 0 V, C_O = 4.7 μF (unless otherwise noted)

PARAMETER		TEST CO	NDITIONS	MIN	TYP	MAX	UNIT	
	TPS76901	$1.2 \text{ V} \le \text{V}_{\text{O}} \le 5.5 \text{ V},$	T _J = 25°C		٧o			
	17376901	$1.2 \text{ V} \le \text{V}_{\text{O}} \le 5.5 \text{ V},$	$T_J = -40^{\circ}C$ to $125^{\circ}C$	0.97V _O		1.03V _O		
	TPS76912	T _J = 25°C,	2.7 V < V _{IN} < 10 V		1.224			
	17370912	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C},$	2.7 V < V _{IN} < 10 V	1.187		1.261		
	TPS76915	$T_J = 25^{\circ}C$,	2.7 V < V _{IN} < 10 V		1.5			
	17370915	$T_J = -40^{\circ}C \text{ to } 125^{\circ}C,$	$2.7 \text{ V} < \text{V}_{IN} < 10 \text{ V}$	1.455		1.545		
	TPS76918	T _J = 25°C,	$2.8 \text{ V} < \text{V}_{IN} < 10 \text{ V}$		1.8			
	11-370918	$T_J = -40^{\circ}C \text{ to } 125^{\circ}C,$	$2.8 \text{ V} < \text{V}_{IN} < 10 \text{ V}$	1.746		1.854		
	TPS76925	T _J = 25°C,	3.5 V < V _{IN} < 10 V		2.5			
Output voltage (10 μA to 100 mA	17370925	$T_J = -40^{\circ}C \text{ to } 125^{\circ}C,$	3.5 V < V _{IN} < 10 V	2.425		2.575	V	
load) (see Note 4)	TPS76927	T _J = 25°C,	3.7 V < V _{IN} < 10 V		2.7		V	
	17370927	$T_J = -40^{\circ}C \text{ to } 125^{\circ}C,$	3.7 V < V _{IN} < 10 V	2.619		2.781		
	TPS76928	T _J = 25°C,	3.8 V < V _{IN} < 10 V		2.8			
	17576926	$T_J = -40^{\circ}C \text{ to } 125^{\circ}C,$	3.8 V < V _{IN} < 10 V	2.716		2.884		
	TDC76020	T _J = 25°C,	4.0 V < V _{IN} < 10 V		3.0			
	TPS76930	$T_J = -40^{\circ}C \text{ to } 125^{\circ}C,$	4.0 V < V _{IN} < 10 V	2.910		3.090		
	TPS76933	T _J = 25°C,	4.3 V < V _{IN} < 10 V		3.3			
		$T_J = -40^{\circ}C \text{ to } 125^{\circ}C,$	4.3 V < V _{IN} < 10 V	3.201		3.399		
	TPS76950	$T_J = 25^{\circ}C$,	6.0 V < V _{IN} < 10 V		5.0			
	17376950	$T_J = -40^{\circ}C \text{ to } 125^{\circ}C,$	6.0 V < V _{IN} < 10 V	4.850		5.150		
Quiescent current (GND current)		EN = 0V, T _J = 25°C	0 mA < I _O < 100 mA,		17		^	
(see Notes 4 and 5)		$\overline{\text{EN}} = 0\text{V},$ $T_{\text{J}} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	I _O = 100 mA,			28	μΑ	
Load regulation		EN = 0V, T _J = 25°C	$I_{O} = 0$ to 100 mA,		12		mV	
Output voltage line regulation ($\Delta V_O/V_O$) (see Note 5)		$V_O + 1 V < V_I \le 10 V$, See Note 4	T _J = 25°C,		0.04		0/ //	
		V_{O} + 1 V < V_{I} \leq 10 V, T_{J} = -40°C to 125°C,	See Note 4			0.1	- %/∨ I	
Output noise voltage		BW = 300 Hz to 50 kH $C_0 = 10 \mu F$,	z, T _J = 25°C		190		μVrms	
Output current limit		$V_{O} = 0 V$	See Note 4		350	750	mA	
Ctoo dhee como at		EN = V _I ,	2.7 < V _I < 10 V		1		μΑ	
Standby current		$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$				2	μΑ	

NOTES: 4. Minimum IN operating voltage is 2.7 V or VO(typ) + 1 V, whichever is greater. Maximum IN voltage 10 V, minimum output current 10 μ A, maximum output current 100 mA. 5. If $V_0 \le 1.8$ V then $V_{lmin} = 2.7$ V, $V_{lmax} = 10$ V:

Line Reg. (mV) =
$$(\%/V) \times \frac{V_O(V_{Imax} - 2.7 \text{ V})}{100} \times 1000$$

If $V_O \ge 2.5 \text{ V}$ then $V_{lmin} = V_O + 1 \text{ V}$, $V_{lmax} = 10 \text{ V}$:

Line Reg. (mV) =
$$(\%/V) \times \frac{V_O(V_{lmax} - (V_O + 1 V))}{100} \times 1000$$



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electrical characteristics over recommended operating free-air temperature range, V_I = V_{O(typ)} + 1 V, I_O = 100 mA, EN = 0 V, C_o = 4.7 μ F (unless otherwise noted) (continued)

PARAMETER		TEST	CONDITIONS	MIN	TYP	MAX	UNIT
FB input current		FB = 1.224 V (TPS	76901)	-1		1	μА
High level enable input voltage		2.7 V < V _I < 10 V		1.7			V
Low level enable input voltage	put current level enable input voltage level enable input voltage	2.7 V < V _I < 10 V				0.9	V
Power supply ripple rejection		f = 1 kHz, T _J = 25°C,	$C_0 = 10 \mu F$, See Note 4		60		dB
Laurent (ENI)		EN = 0 V		-1	0	1	μΑ
Input current (EN)		EN = V _I		-1		1	μΑ
		I _O = 50 mA,	T _J = 25°C		60		
	TPS76928	I _O = 50 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			125	
	17576926	I _O = 100 mA,	T _J = 25°C		122		
		I _O = 100 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			245	
		I _O = 50 mA,	T _J = 25°C		57		
	TD076020	I _O = 50 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			115	
	17-37-0930	I _O = 100 mA,	T _J = 25°C		115		
Dropout voltage (see Note 6)		$I_O = 100 \text{ mA},$	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			230	mV
Diopout voltage (see Note 6)		$I_O = 50 \text{ mA},$	T _J = 25°C		48		IIIV
	TD076022	I _O = 50 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			100	
	17-37-0933	I _O = 100 mA,	T _J = 25°C		98		
		I _O = 100 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			200	
		I _O = 50 mA,	T _J = 25°C		35		
	TP\$76050	I _O = 50 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			85	
	11 370930	$I_0 = 100 \text{ mA},$	T _J = 25°C		71		
		$I_O = 100 \text{ mA},$	$T_J = -40^{\circ}\text{C to } 125^{\circ}\text{C}$			170	

- NOTES: 4. Minimum IN operating voltage is 2.7 V or $V_{O(typ)}$ + 1 V, whichever is greater. Maximum IN voltage 10 V, minimum output current 10 μ A, maximum output current 100 mA.
 - 6. IN voltage equals V_O(Typ) 100mV; TPS76901 output voltage set to 3.3V nominal with external resistor divider. TPS76912, TPS76915, TPS76918, TPS76925, and TPS76927 dropout voltage limited by input voltage range limitations.

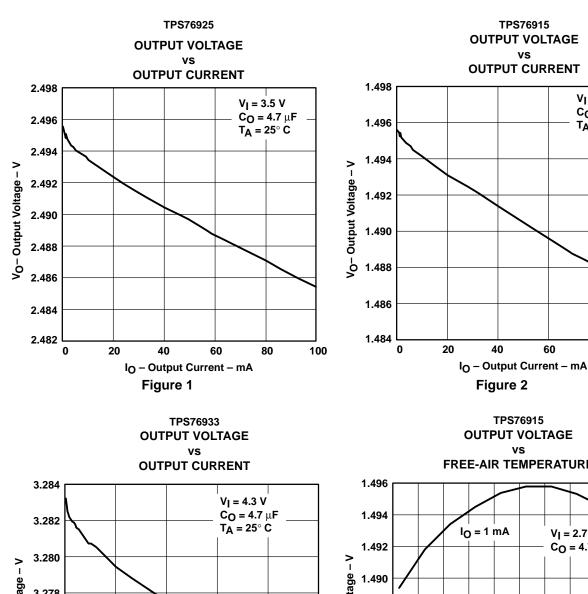
TYPICAL CHARACTERISTICS

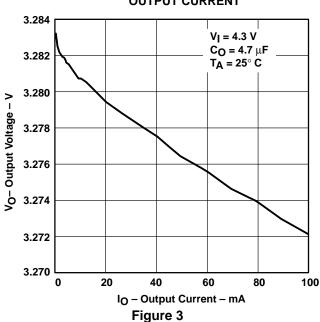
Table of Graphs

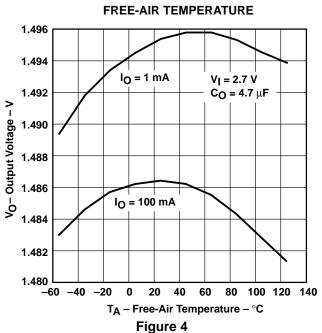
			FIGURE
Va	Output voltage	vs Output current	1, 2, 3
> 0	Output voltage	vs Free-air temperature	4, 5, 6
	Ground current	vs Free-air temperature	7
	Output spectral noise density	vs Frequency	8
Z _O	Output impedance	vs Frequency	9
V_{DO}	Dropout voltage	vs Free-air temperature	10
	Ripple rejection	vs Frequency	11
	LDO startup time		12
	Line transient response		13, 15
	Load transient response		14, 16
	Faulty cleant continue registering (FSD)	vs Output current	17, 19
	Equivalent series resistance (ESR)	vs Added ceramic capacitance	18, 20



TYPICAL CHARACTERISTICS







 $V_{I} = 2.7 V$

 $C_O = 4.7 \,\mu\text{F}$

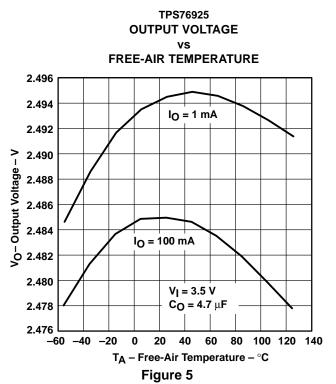
 $T_A = 25^{\circ} C$

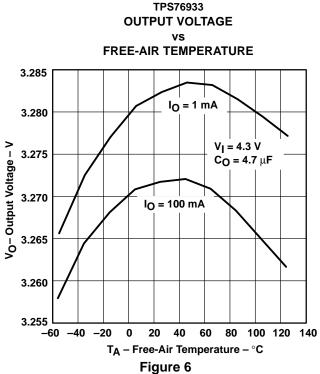
80

100



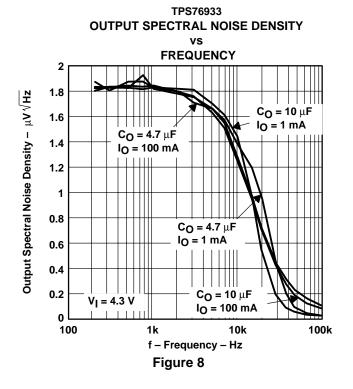
TYPICAL CHARACTERISTICS



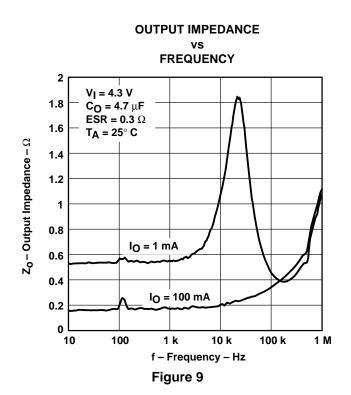


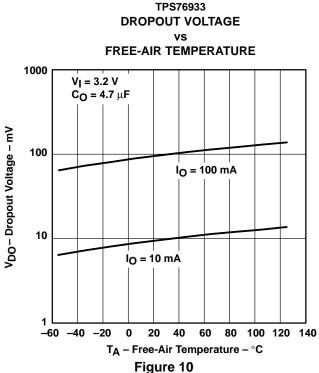
GROUND CURRENT vs FREE-AIR TEMPERATURE 22 $V_{I} = 4.3 V$ $C_0 = 4.7 \, \mu F$ 21 20 Ground Current - µA $I_0 = 100 \text{ mA}$ 19 18 $I_O = 0 \text{ mA}$ 17 16 15 **–**60 **–**40 **–**20 40 0 60 80 100 120 140 T_A - Free-Air Temperature - °C Figure 7

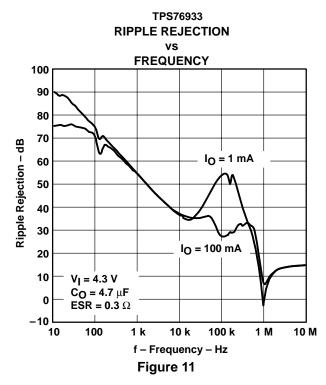
TPS76933

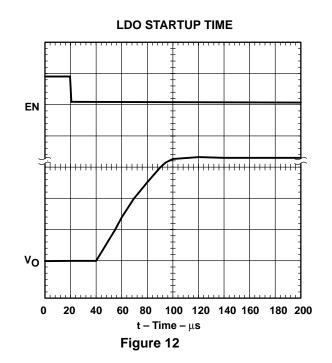


TYPICAL CHARACTERISTICS









TYPICAL CHARACTERISTICS

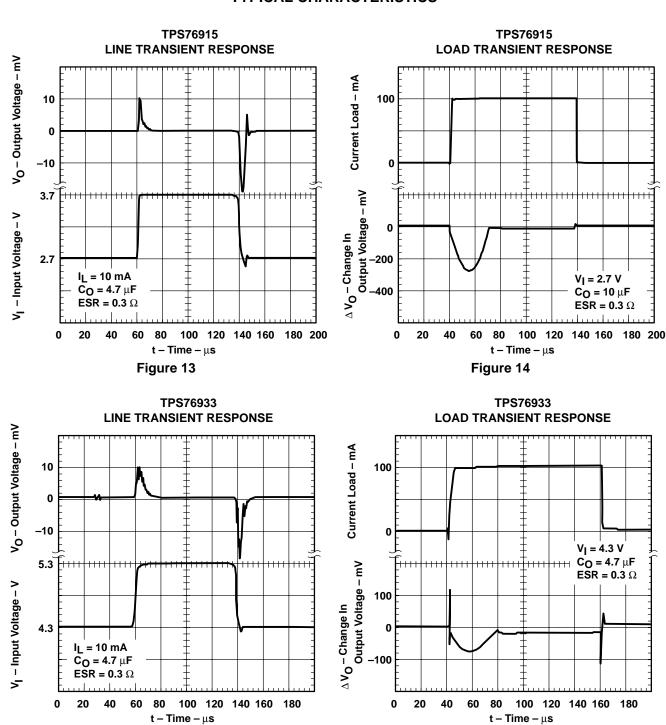


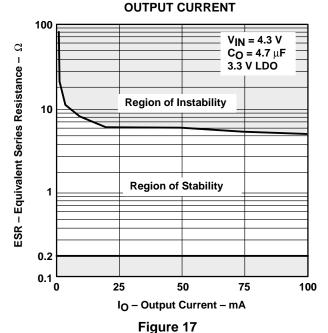


Figure 16

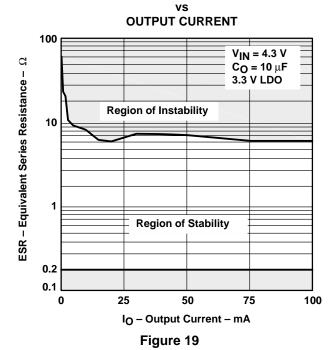
Figure 15

TYPICAL CHARACTERISTICS

TPS76933 TYPICAL REGIONS OF STABILITY EQUIVALENT SERIES RESISTANCE (ESR)† vs



TPS76933
TYPICAL REGIONS OF STABILITY
EQUIVALENT SERIES RESISTANCE (ESR)†



TPS76933 TYPICAL REGIONS OF STABILITY EQUIVALENT SERIES RESISTANCE (ESR)

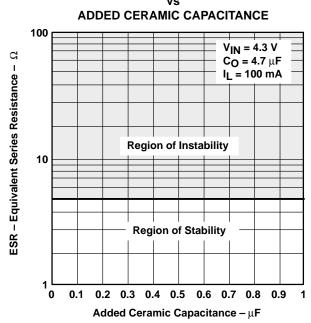


Figure 18

TPS76933 TYPICAL REGIONS OF STABILITY EQUIVALENT SERIES RESISTANCE (ESR)

ADDED CERAMIC CAPACITANCE

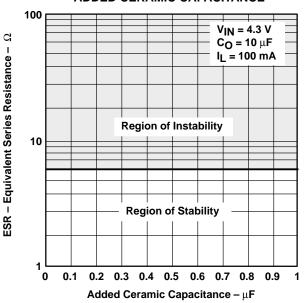


Figure 20



APPLICATION INFORMATION

The TPS769xx family of low-dropout (LDO) regulators have been optimized for use in battery-operated equipment. They feature extremely low dropout voltages, low quiescent current (17 μ A nominally), and enable inputs to reduce supply currents to 1 μ A when the regulators are turned off.

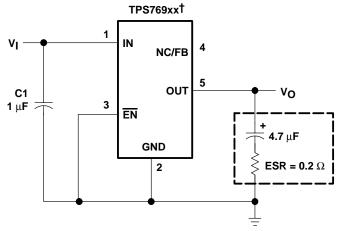
device operation

The TPS769xx uses a PMOS pass element to dramatically reduce both dropout voltage and supply current over more conventional PNP-pass-element LDO designs. The PMOS pass element is a voltage-controlled device and, unlike a PNP transistor, it does not require increased drive current as output current increases. Supply current in the TPS769xx is essentially constant from no load to maximum load.

Current limiting and thermal protection prevent damage by excessive output current and/or power dissipation. The device switches into a constant-current mode at approximately 350 mA; further load reduces the output voltage instead of increasing the output current. The thermal protection shuts the regulator off if the junction temperature rises above approximately 165°C. Recovery is automatic when the junction temperature drops approximately 25°C below the high temperature trip point. The PMOS pass element includes a back gate diode that conducts reverse current when the input voltage level drops below the output voltage level.

A voltage of 1.7 V or greater on the \overline{EN} input will disable the TPS769xx internal circuitry, reducing the supply current to 1 μ A. A voltage of less than 0.9 V on the \overline{EN} input will enable the TPS769xx and will enable normal operation to resume. The \overline{EN} input does not include any deliberate hysteresis, and it exhibits an actual switching threshold of approximately 1.5 V.

A typical application circuit is shown in Figure 21.



† TPS76912, TPS76915, TPS76918, TPS76925, TPS76927, TPS76928, TPS76930, TPS76933, TPS76950 (fixed-voltage options).

Figure 21. Typical Application Circuit



APPLICATION INFORMATION

external capacitor requirements

Although not required, a 0.047-μF or larger ceramic input bypass capacitor, connected between IN and GND and located close to the TPS769xx, is recommended to improve transient response and noise rejection. A higher-value electrolytic input capacitor may be necessary if large, fast-rise-time load transients are anticipated and the device is located several inches from the power source.

Like all low dropout regulators, the TPS769xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance is 4.7 μF . The ESR (equivalent series resistance) of the capacitor should be between 0.2 Ω and 10 Ω . to ensure stability. Capacitor values larger than 4.7 μF are acceptable, and allow the use of smaller ESR values. Capacitances less than 4.7 μF are not recommended because they require careful selection of ESR to ensure stability. Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Most of the commercially available 4.7 μF surface-mount solid tantalum capacitors, including devices from Sprague, Kemet, and Nichico, meet the ESR requirements stated above. Multilayer ceramic capacitors may have very small equivalent series resistances and may thus require the addition of a low value series resistor to ensure stability.

CAPACITOR SELECTION

PART NO.	MFR.	VALUE	MAX ESR†	SIZE $(H \times L \times W)^{\dagger}$
T494B475K016AS	KEMET	4.7 μF	$1.5~\Omega$	$1.9 \times 3.5 \times 2.8$
195D106x0016x2T	SPRAGUE	10 μF	$1.5~\Omega$	$1.3\times7.0\times2.7$
695D106x003562T	SPRAGUE	10 μF	$1.3~\Omega$	$2.5\times7.6\times2.5$
TPSC475K035R0600	AVX	4.7 μF	$0.6~\Omega$	$2.6\times6.0\times3.2$

[†] Size is in mm. ESR is maximum resistance in Ohms at 100 kHz and T_A = 25°C. Contact manufacturer for minimum ESR values.



APPLICATION INFORMATION

output voltage programming

The output voltage of the TPS76901 adjustable regulator is programmed using an external resistor divider as shown in Figure 22. The output voltage is calculated using:

$$V_{O} = V_{ref} \times \left(1 + \frac{R1}{R2}\right) \tag{1}$$

Where:

 $V_{ref} = 1.224 \text{ V typ (the internal reference voltage)}$

Resistors R1 and R2 should be chosen for approximately 7- μ A divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided as leakage currents at FB increase the output voltage error. The recommended design procedure is to choose R2 = 169 k Ω to set the divider current at 7 μ A and then calculate R1 using:

$$R1 = \left(\frac{V_{O}}{V_{ref}} - 1\right) \times R2 \tag{2}$$

OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE		ESISTANCE Ω)‡
(V)	R1	R2
2.5	174	169
3.3	287	169
3.6	324	169
4.0	383	169
5.0	523	169



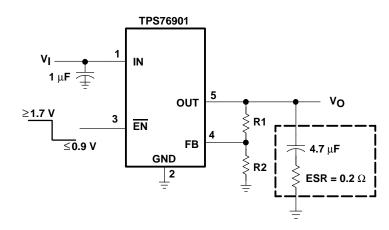


Figure 22. TPS76901 Adjustable LDO Regulator Programming

APPLICATION INFORMATION

power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of 125° C; the maximum junction temperature should be restricted to 125° C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, $P_{D(max)}$, and the actual dissipation, P_{D} , which must be less than or equal to $P_{D(max)}$.

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_{J}max - T_{A}}{R_{\theta,JA}}$$

Where:

T_Jmax is the maximum allowable junction temperature

R_{0.JA} is the thermal resistance junction-to-ambient for the package, see the dissipation rating table.

T_A is the ambient temperature.

The regulator dissipation is calculated using:

$$P_D = (V_I - V_O) \times I_O$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.

regulator protection

The TPS769xx PMOS-pass transistor has a built-in back diode that conducts reverse current when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. If extended reverse voltage operation is anticipated, external limiting might be appropriate.

The TPS769xx features internal current limiting and thermal protection. During normal operation, the TPS769xx limits output current to approximately 350 mA. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds approximately 165°C, thermal-protection circuitry shuts it down. Once the device has cooled down to below approximately 140°C, regulator operation resumes.







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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TPS76901DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCFI	Samples
TPS76901DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCFI	Samples
TPS76901DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCFI	Samples
TPS76901DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCFI	Samples
TPS76912DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCGI	Samples
TPS76912DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCGI	Samples
TPS76912DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCGI	Samples
TPS76912DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCGI	Samples
TPS76915DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCHI	Samples
TPS76915DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCHI	Samples
TPS76915DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCHI	Samples
TPS76915DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCHI	Samples
TPS76918DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCII	Samples
TPS76918DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCII	Samples
TPS76918DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCII	Samples
TPS76918DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCII	Samples
TPS76925DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCJI	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TPS76925DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCJI	Samples
TPS76925DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCJI	Samples
TPS76925DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCJI	Samples
TPS76927DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCKI	Samples
TPS76927DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCKI	Samples
TPS76927DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCKI	Samples
TPS76928DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCLI	Samples
TPS76928DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCLI	Samples
TPS76928DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCLI	Samples
TPS76928DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCLI	Samples
TPS76930DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCMI	Samples
TPS76930DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCMI	Samples
TPS76930DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCMI	Samples
TPS76930DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCMI	Samples
TPS76933DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCNI	Samples
TPS76933DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCNI	Sample
TPS76933DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCNI	Sample
TPS76933DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCNI	Sample



PACKAGE OPTION ADDENDUM

12-Sep-2016

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TPS76950DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCOI	Samples
TPS76950DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCOI	Samples
TPS76950DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCOI	Samples
TPS76950DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PCOI	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

12-Sep-2016

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OTHER QUALIFIED VERSIONS OF TPS769:

Automotive: TPS769-Q1

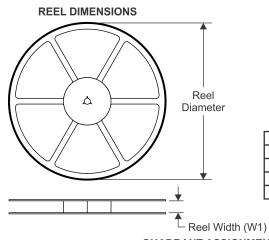
NOTE: Qualified Version Definitions:

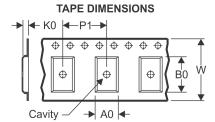
• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

www.ti.com 20-Dec-2016

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



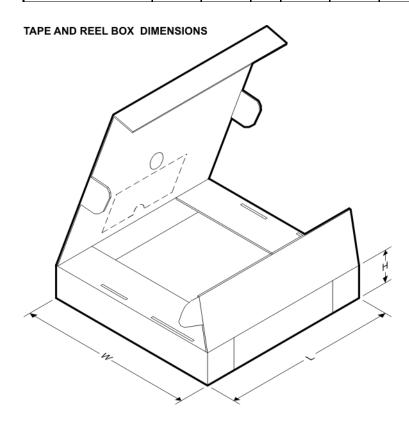
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS76901DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76901DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76912DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76912DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76915DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76915DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76918DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76918DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76925DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76925DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76927DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS76927DBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TPS76928DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76928DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76930DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76930DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76933DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS76933DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

PACKAGE MATERIALS INFORMATION

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Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS76933DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76933DBVT	SOT-23	DBV	5	250	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS76950DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76950DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3



*All dimensions are nominal

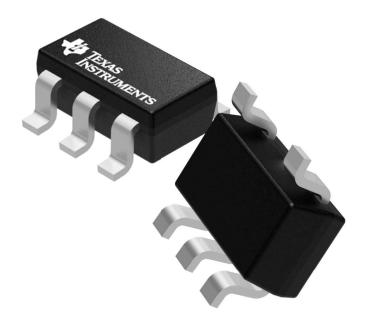
All differisions are nominal	1						1
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS76901DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76901DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS76912DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76912DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS76915DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76915DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS76918DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76918DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS76925DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76925DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS76927DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76927DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS76928DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0



PACKAGE MATERIALS INFORMATION

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS76928DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS76930DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76930DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS76933DBVR	SOT-23	DBV	5	3000	210.0	185.0	35.0
TPS76933DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76933DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS76933DBVT	SOT-23	DBV	5	250	210.0	185.0	35.0
TPS76950DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76950DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0



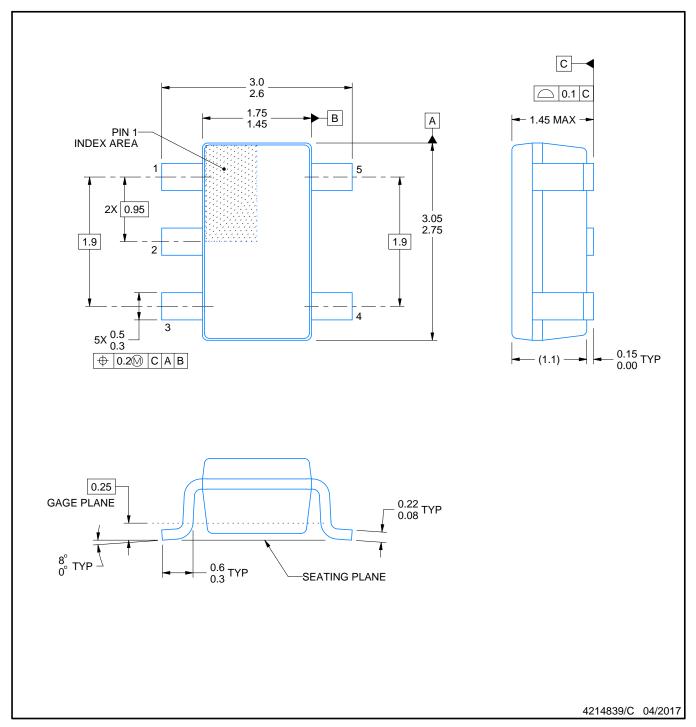
Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4073253/P





SMALL OUTLINE TRANSISTOR



NOTES:

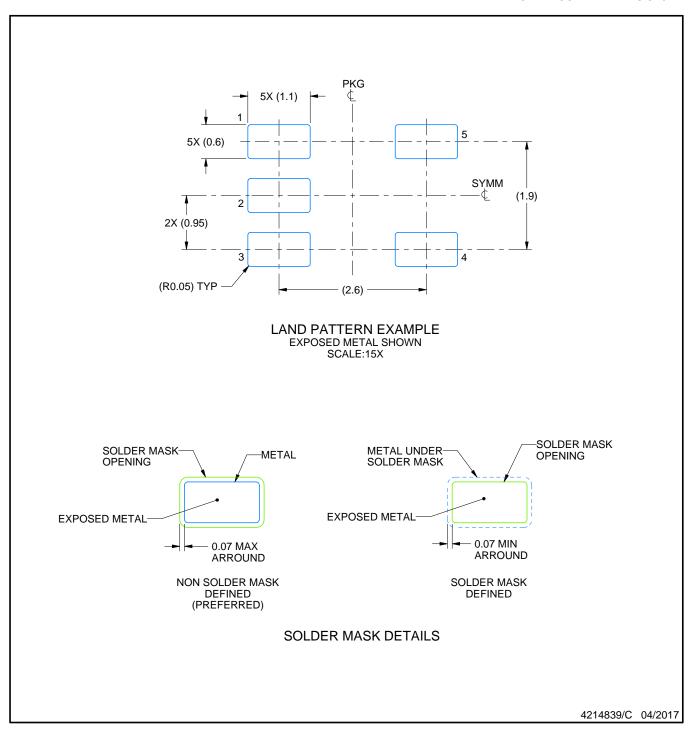
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. Reference JEDEC MO-178.



SMALL OUTLINE TRANSISTOR

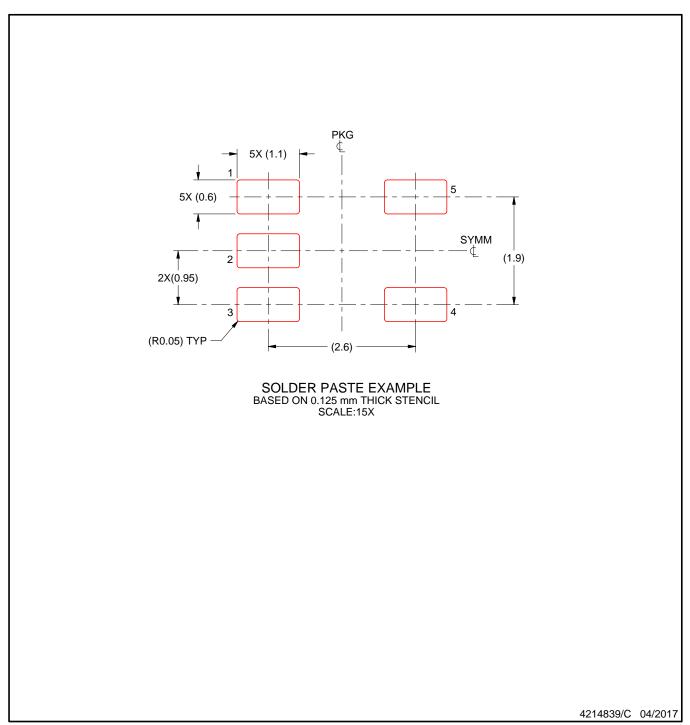


NOTES: (continued)

- 4. Publication IPC-7351 may have alternate designs.
- 5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 7. Board assembly site may have different recommendations for stencil design.



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